

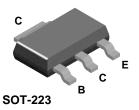
2N3906

MMBT3906

PZT3906







PNP General Purpose Amplifier

This device is designed for general purpose amplifier and switching applications at collector currents of 10 μA to 100 mA.

Absolute Maximum Ratings*

 $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Value	Units	
V _{CEO}	Collector-Emitter Voltage	40	V	
V _{CBO}	Collector-Base Voltage	40	V	
V _{EBO}	Emitter-Base Voltage	5.0	V	
I _C	Collector Current - Continuous	200	mA	
T _J , T _{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C	

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.
 3) All voltages (V) and currents (A) are negative polarity for PNP transistors.

Thermal Characteristics T_A = 25°C unless otherwise noted

Symbol	Characteristic	Max		Units	
		2N3906	*MMBT3906	**PZT3906	
P_D	Total Device Dissipation	625	350	1,000	mW
	Derate above 25°C	5.0	2.8	8.0	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	83.3			°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	357	125	°C/W

^{*}Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

^{**}Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm; mounting pad for the collector lead min. 6 cm².

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T_A = 25°C unless otherwise noted

Parameter Test Conditions		Min	Max	Units
RACTERISTICS				
Collector-Emitter Breakdown Voltage*	$I_C = 1.0 \text{ mA}, I_B = 0$	40		V
Collector-Base Breakdown Voltage	$I_C = 10 \mu A, I_E = 0$	40		V
Emitter-Base Breakdown Voltage	$I_E = 10 \mu\text{A}, I_C = 0$	5.0		V
Base Cutoff Current	$V_{CE} = 30 \text{ V}, V_{BE} = 3.0 \text{ V}$		50	nA
Collector Cutoff Current	$V_{CE} = 30 \text{ V}, V_{BE} = 3.0 \text{ V}$		50	nA
	RACTERISTICS Collector-Emitter Breakdown Voltage* Collector-Base Breakdown Voltage Emitter-Base Breakdown Voltage Base Cutoff Current	RACTERISTICS Collector-Emitter Breakdown Voltage* $I_C = 1.0 \text{ mA}, I_B = 0$ Collector-Base Breakdown Voltage $I_C = 10 \mu\text{A}, I_C = 0$ Emitter-Base Breakdown Voltage $I_E = 10 \mu\text{A}, I_C = 0$ Base Cutoff Current $V_{CE} = 30 \text{ V}, V_{BE} = 3.0 \text{ V}$	RACTERISTICS Collector-Emitter Breakdown Voltage* $I_C = 1.0 \text{ mA}, I_B = 0$ 40 Collector-Base Breakdown Voltage $I_C = 10 \mu\text{A}, I_E = 0$ 40 Emitter-Base Breakdown Voltage $I_E = 10 \mu\text{A}, I_C = 0$ 5.0 Base Cutoff Current $V_{CE} = 30 \text{ V}, V_{BE} = 3.0 \text{ V}$	RACTERISTICS Collector-Emitter Breakdown Voltage* $I_C = 1.0 \text{ mA}, I_B = 0$ 40 Collector-Base Breakdown Voltage $I_C = 10 \mu\text{A}, I_C = 0$ 40 Emitter-Base Breakdown Voltage $I_E = 10 \mu\text{A}, I_C = 0$ 5.0 Base Cutoff Current $V_{CE} = 30 \text{ V}, V_{BE} = 3.0 \text{ V}$ 50

ON CHARACTERISTICS

h _{FE}	DC Current Gain *	$I_{\rm C} = 0.1 \text{ mA}, V_{\rm CE} = 1.0 \text{ V}$	60		
		$I_C = 1.0 \text{ mA}, V_{CE} = 1.0 \text{ V}$	80		
		$I_C = 10 \text{ mA}, V_{CE} = 1.0 \text{ V}$	100	300	
		$I_C = 50 \text{ mA}, V_{CE} = 1.0 \text{ V}$	60		
		$I_C = 100 \text{ mA}, V_{CE} = 1.0 \text{ V}$	30		
V _{CE(sat)}	Collector-Emitter Saturation Voltage	$I_C = 10 \text{ mA}, I_B = 1.0 \text{ mA}$		0.25	V
		$I_C = 50 \text{ mA}, I_B = 5.0 \text{ mA}$		0.4	V
V _{BE(sat)}	Base-Emitter Saturation Voltage	$I_C = 10 \text{ mA}, I_B = 1.0 \text{ mA}$	0.65	0.85	V
, , ,		$I_C = 50 \text{ mA}, I_B = 5.0 \text{ mA}$		0.95	V

SMALL SIGNAL CHARACTERISTICS

f⊤	Current Gain - Bandwidth Product	$I_C = 10 \text{ mA}, V_{CE} = 20 \text{ V},$	250		MHz
		f = 100 MHz			
Cobo	Output Capacitance	$V_{CB} = 5.0 \text{ V}, I_{E} = 0,$		4.5	pF
020		f = 100 kHz			
Cibo	Input Capacitance	$V_{EB} = 0.5 \text{ V}, I_{C} = 0,$		10.0	pF
		f = 100 kHz			-
NF	Noise Figure	$I_C = 100 \mu A, V_{CE} = 5.0 V,$		4.0	dB
		$R_S = 1.0 \text{k}\Omega, f = 10 \text{ Hz to } 15.7 \text{ kHz}$			

SWITCHING CHARACTERISTICS

t _d	Delay Time	$V_{CC} = 3.0 \text{ V}, V_{BE} = 0.5 \text{ V},$	35	ns
t _r	Rise Time	$I_C = 10 \text{ mA}, I_{B1} = 1.0 \text{ mA}$	35	ns
t _s	Storage Time	$V_{CC} = 3.0 \text{ V}, I_{C} = 10\text{mA}$	225	ns
t _f	Fall Time	$I_{B1} = I_{B2} = 1.0 \text{ mA}$	75	ns

^{*}Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%

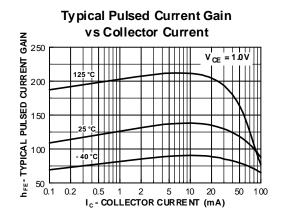
NOTE: All voltages (V) and currents (A) are negative polarity for PNP transistors.

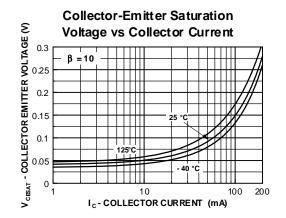
Spice Model

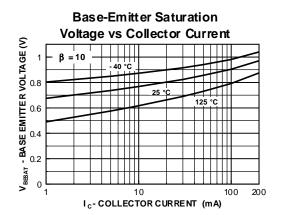
PNP (Is=1.41f Xti=3 Eg=1.11 Vaf=18.7 Bf=180.7 Ne=1.5 Ise=0 Ikf=80m Xtb=1.5 Br=4.977 Nc=2 Isc=0 Ikr=0 Rc=2.5 Cjc=9.728p Mjc=.5776 Vjc=.75 Fc=.5 Cje=8.063p Mje=.3677 Vje=.75 Tr=33.42n Tf=179.3p Itf=.4 Vtf=4 Xtf=6 Rb=10)

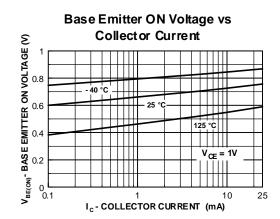
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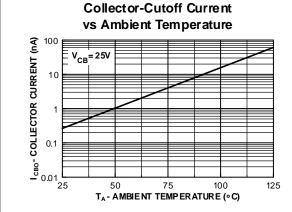
Typical Characteristics

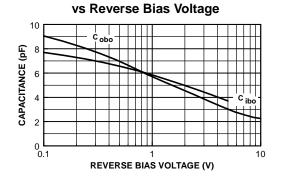










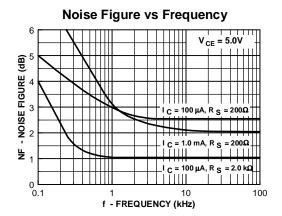


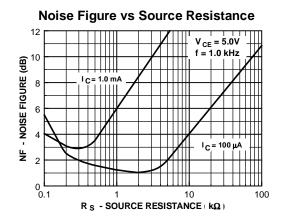
Common-Base Open Circuit

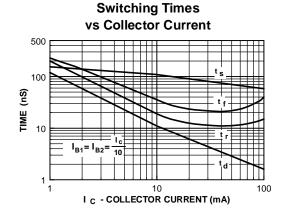
Input and Output Capacitance

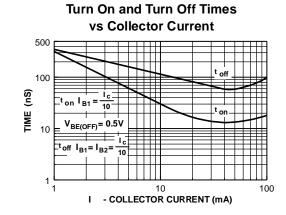
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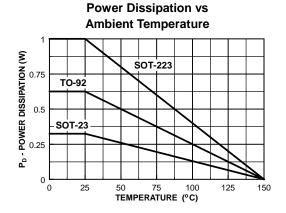
Typical Characteristics (continued)





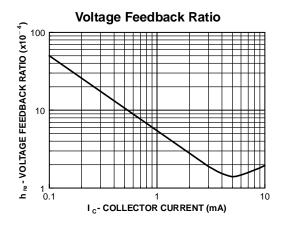


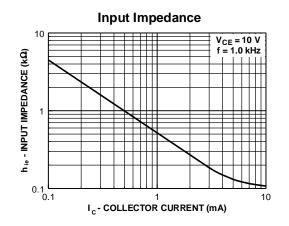


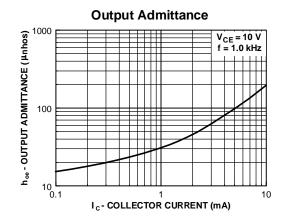


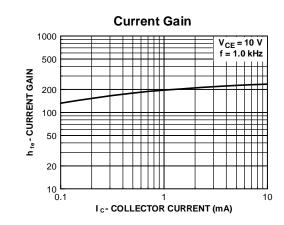
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Typical Characteristics (continued)









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